

Qualification Results Summary of Sumitomo G770SHC (Low Alpha Mold Compound) at UTAC

QUALIFICATION STATUS – LTC2977 64L QFN			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	77	Pass
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	77	Pass
Unbiased Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A118</i>	77	Pass
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	77	Pass
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	231	Pass

*Preconditioned per JEDEC/IPC J-STD-020

Qualification Results Summary of Sumitomo G770SHC (Low Alpha Mold Compound) at UTAC

QUALIFICATION STATUS – LTC3882 40L QFN			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
High Temperature Operating Life (HTOL)	JEDEC <i>JESD22-A108</i>	77	Pass
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	77	Pass
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	77	Pass
Unbiased Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A118</i>	77	Pass
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	77	Pass
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	231	Pass

*Preconditioned per JEDEC/IPC J-STD-020

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